


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F217ZGT6	P01A*411XXX3	A	9998	20-11-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20x1.4	144	L Bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P01A*411XXX3				6000001.0	1000002.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.627	mg	supplier	die	Silicon (Si)	7440-21-3		9.945	mg	935824	7563
				supplier	metallization	Aluminium (Al)	7429-90-5		0.048	mg	4517	37
				supplier	metallization	Copper (Cu)	7440-50-8		0.310	mg	29171	236
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	94	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.043	mg	4046	33
				supplier	metallization	Tungsten (W)	7440-33-7		0.139	mg	13080	106
				supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	3388	27
				supplier	Passivation	Silicon Oxide	7631-86-9		0.105	mg	9880	80
				supplier	ALLOY	Copper (Cu)	7440-50-8		234.008	mg	975000	177953
LEADFRAME (MHT- C194)	M-011 Other inorganic materials	240.008	mg	supplier	ALLOY	Iron (Fe)	7439-89-6		5.640	mg	23500	4289
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.288	mg	1200	219
				supplier	ALLOY	Metallic Phosphorus (P)	7723-14-0		0.072	mg	300	55
				supplier	COATING	Nickel (Ni)	7440-02-0		10.188	mg	970000	7748
LEADFRAME (MHT - PPF Plating)	M-011 Other inorganic materials	10.503	mg	supplier	COATING	Palladium (Pd)	7440-05-3		0.158	mg	15000	120
				supplier	COATING	Gold (Au)	7440-57-5		0.158	mg	15000	120
				supplier	GLUE	Silver(Ag)	7440-22-4		2.030	mg	700000	1544
DIE ATTACH (Sumitomo - CRM-1076Y)	M-011 Other inorganic materials	2.900	mg	supplier	GLUE	Epoxy Resin A	9003-36-5		0.145	mg	50000	110
				supplier	GLUE	Silica fused (SiO2)	7631-86-9		0.290	mg	100000	221
				supplier	GLUE	Dicyandiamide	461-58-5		0.015	mg	5000	11
				supplier	GLUE	Diluent	3101-60-8		0.145	mg	50000	110
				supplier	GLUE	Allyl Compound	Proprietary		0.145	mg	50000	110
				supplier	GLUE	Hardener	Proprietary		0.131	mg	45000	99
				supplier	GLUE	Hardener	Proprietary		0.131	mg	45000	99
BONDING WIRE (Heesung - Au HTS)	M-011 Other inorganic materials	2.529	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.504	mg	990050	1904
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.025	mg	9900	19
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	50	0
ENCAPSULATION (Sumitomo - G631H)	M-011 Other inorganic materials	1045.853	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		20.737	mg	19779	15769
				supplier	MOLDING COMPOUND	Epoxy Resin B	85954-11-6		41.474	mg	39558	31539
				supplier	MOLDING COMPOUND	Silica Amorphous A	60676-86-0		825.512	mg	787378	627766
				supplier	MOLDING COMPOUND	Silica Amorphous B	7631-86-9		88.131	mg	84060	67020
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		5.184	mg	4945	3942
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		67.395	mg	64281	51251